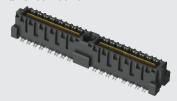






Integral metal plane



QMS SERIES

(0,635 mm) .025"

GGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material: Liquid Crystal Polymer Terminal & Ground Plane Material: Phosphor Bronze Plating: Au over 50μ" (1,27 μm) Ni (Tin on Ground Plane Tail)

Current Rating: Contact: 2.6 A per pin 2.6 A per pin
(1 pin powered per row)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered)

Voltage Rating: 300 VAC mated with QFS Operating Temp: -55°C to +125°C RoHS Compliant: Yes

Processing: Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (026-052) (0,15 mm) .006" max (078)

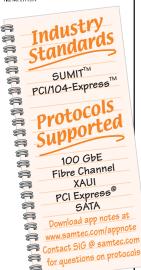
Board Stacking: For applications requiring more than two connectors per board,

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

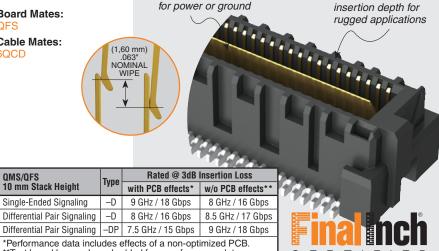
contact ipg@samtec.com





Note: Some lengths, styles and options are non-standard, non-returnable. **Board Mates:**

Cable Mates:



ALSO AVAILABLE (MOQ Required)

- Other platings
- Guide Posts
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row Contact Samtec.

Gbps

PINS PER ROW **LEAD** ${\sf QMS}$ STYLE NO. OF PAIRS

-026, -052, -078 (52 total pins per bank = -D)

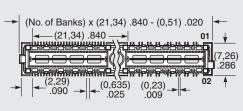
Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

-016, -032, -048 (16 pairs per bank = -D-DP)

Specify LEAD **STYLE** from chart

MATED HEIGHT* QFS LEAD STYLE **LEAD** Α STYLE -04.25 -06.25 **-05.75** (5,38) .212 10 mm 12 mm **-06.75** (6,35) .250 11 mm 13 mm **-09.75** (9,35) .368 14 mm 16 mm *Processing conditions will affect mated height.

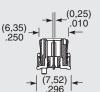




PLATING OPTION

-05.75 and -06.75 lead style only) = 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

(–09.75 lead style only) 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)



–D = Single-Ended -D-DP

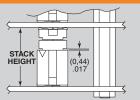
= Differential Pair

-K (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

OTHER

OPTION

APPLICATION



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm